DETAILED ACTION

EXAMINER'S AMENDMENT

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Ms. Laura Kelly on 12/17/08.

The application has been amended as follows:

Please, cancel claims 29-30, and 34-35 without prejudice.

Claims 28, 31-33, and 36 are now amended as shown below:

- 28. (**Currently Amended**) A conductive structure comprising:
- a first conductor;
- a plurality of atomic layers of a second conductor directly on the first conductor;

a first solid material directly on the plurality of atomic layers of the second conductor, remote from the first conductor, the first material being penetrable by the plurality of atomic layers of the second conductor relative to at least a second material other than the second conductor;

wherein the first conductor comprises a platinum group metal, the first
material comprises a halogen, the second conductor comprises a metal and the
second material comprises oxygen; the structure further comprising a substrate

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on the first conductor, remote from the plurality of atomic layers of the second conductor.

- 31. (<u>Currently Amended</u>) A <u>The</u> structure according to Claim 30 28 wherein the substrate comprises an integrated circuit wafer.
- 32. (**Currently Amended**) A **The** structure according to Claim 28 wherein the first material comprises about a monolayer of the first material.
 - 33. (Currently Amended) A conductive structure comprising:
 - a first layer comprising ruthenium;

a second layer comprising a plurality of atomic layers of copper directly on the first layer comprising ruthenium; and

a third layer comprising iodine directly on the second layer comprising a plurality of atomic layers of copper, remote from the first layer comprising ruthenium;

wherein the third layer comprises about one monolayer of iodine, the structure further comprising a substrate on the first layer, remote from the second layer.

36. (<u>Currently Amended</u>) A **The** structure according to Claim 35 <u>33</u> wherein the substrate comprises an integrated circuit wafer.

Allowable Subject Matter

2. Claims 28, 31-33, and 36 are allowed (renumber claims are 1-5).

The following is an examiner's statement of reasons for allowance: Amended claims have been considered and upon conclusion of a comprehensive search of the prior arts. The Office indicates that the claims, as amended, are allowable.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

3. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Norman et al., Chu et al. disclose related art.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan T. Dinh whose telephone number is 571-272-1929. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Reichard Dean can be reached on 571-272-1984. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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/Tuan T Dinh/ Primary Examiner, Art Unit 2841.